WHAT IS CLAIMED IS:

1. A method of manufacturing a display device comprising:

forming a thin film transistor over a substrate, the thin film transistor comprising a semiconductor region and a gate electrode with a gate insulating film interposed therebetween;

forming a first layer comprising titanium on the semiconductor region; forming a second layer comprising aluminum on the first layer; forming a third layer comprising titanium on the second layer; and forming a pixel electrode comprising a conductive oxide film on the third layer.

- 2. A method of manufacturing a display device according to claim 1 wherein the semiconductor region comprises crystalline silicon.
- 3. A method of manufacturing a display device according to claim 1 wherein the conductive oxide film comprises one selected from the group consisting of indium tin oxide, zinc oxide, and nickel oxide.
- 4. A method of manufacturing a display device according to claim 1 wherein the first layer comprises titanium nitride.
- 5. A method of manufacturing a display device according to claim 1 wherein the second layer comprises aluminum containing 1% silicon.
- 6. A method of manufacturing a display device according to claim 1 wherein the third layer comprises titanium nitride.
- 7. A method of manufacturing a display device according to claim 1 wherein the gate electrode comprises at least one selected from the group consisting of aluminum, silicon, titanium, tantalum, tungsten, and molybdenum.
- 8. A method of manufacturing a display device according to claim 1 wherein the gate electrode is formed over the semiconductor region.
- 9. A method of manufacturing a display device according to claim 1 wherein the display device is an active matrix type liquid crystal display device.
 - 10. A method of manufacturing a display device comprising:

forming a thin film transistor over a substrate, the thin film transistor comprising a semiconductor region and a gate electrode with a gate insulating film interposed therebetween;

forming a first layer comprising titanium on the semiconductor region; forming a second layer comprising aluminum on the first layer; forming a third layer comprising titanium on the second layer; forming a conductive oxide film on the third layer; and patterning the conductive oxide film so as to form a pixel electrode.

- 11. A method of manufacturing a display device according to claim 10 wherein the semiconductor region comprises crystalline silicon.
- 12. A method of manufacturing a display device according to claim 10 wherein the conductive oxide film comprises one selected from the group consisting of indium tin oxide, zinc oxide, and nickel oxide.
- 13. A method of manufacturing a display device according to claim 10 wherein the first layer comprises titanium nitride.
- 14. A method of manufacturing a display device according to claim 10 wherein the second layer comprises aluminum containing 1% silicon.
- 15. A method of manufacturing a display device according to claim 10 wherein the third layer comprises titanium nitride.
- 16. A method of manufacturing a display device according to claim 10 wherein the gate electrode comprises at least one selected from the group consisting of aluminum, silicon, titanium, tantalum, tungsten, and molybdenum.
- 17. A method of manufacturing a display device according to claim 10 wherein the gate electrode is formed over the semiconductor region.
- 18. A method of manufacturing a display device according to claim 10 wherein the display device is an active matrix type liquid crystal display device.
 - 19. A method of manufacturing a display device comprising:

forming a thin film transistor over a substrate, the thin film transistor comprising a semiconductor region and a gate electrode with a gate insulating film interposed

therebetween;

forming a first layer comprising titanium on the semiconductor region; forming a second layer comprising aluminum on the first layer; forming a third layer comprising titanium on the second layer; patterning the first to third layers so as to form an electrode; and forming a pixel electrode comprising a conductive oxide film on the third layer of the electrode.

- 20. A method of manufacturing a display device according to claim 19 wherein the semiconductor region comprises crystalline silicon.
- 21. A method of manufacturing a display device according to claim 19 wherein the conductive oxide film comprises one selected from the group consisting of indium tin oxide, zinc oxide, and nickel oxide.
- 22. A method of manufacturing a display device according to claim 19 wherein the first layer comprises titanium nitride.
- 23. A method of manufacturing a display device according to claim 19 wherein the second layer comprises aluminum containing 1% silicon.
- 24. A method of manufacturing a display device according to claim 19 wherein the third layer comprises titanium nitride.
- 25. A method of manufacturing a display device according to claim 19 wherein the gate electrode comprises at least one selected from the group consisting of aluminum, silicon, titanium, tantalum, tungsten, and molybdenum.
- 26. A method of manufacturing a display device according to claim 19 wherein the gate electrode is formed over the semiconductor region.
- 27. A method of manufacturing a display device according to claim 19 wherein the display device is an active matrix type liquid crystal display device.
 - 28. A method of manufacturing a display device comprising:

forming a thin film transistor over a substrate, the thin film transistor comprising a semiconductor region and a gate electrode with a gate insulating film interposed therebetween;

forming a first layer comprising titanium on the semiconductor region; forming a second layer comprising aluminum on the first layer; forming a third layer comprising titanium on the second layer; patterning the first to third layers so as to form an electrode; forming a conductive oxide film on the third layer of the electrode; and patterning the conductive oxide film so as to form a pixel electrode.

- 29. A method of manufacturing a display device according to claim 28 wherein the semiconductor region comprises crystalline silicon.
- 30. A method of manufacturing a display device according to claim 28 wherein the conductive oxide film comprises one selected from the group consisting of indium tin oxide, zinc oxide, and nickel oxide.
- 31. A method of manufacturing a display device according to claim 28 wherein the first layer comprises titanium nitride.
- 32. A method of manufacturing a display device according to claim 28 wherein the second layer comprises aluminum containing 1% silicon.
- 33. A method of manufacturing a display device according to claim 28 wherein the third layer comprises titanium nitride.
- 34. A method of manufacturing a display device according to claim 28 wherein the gate electrode comprises at least one selected from the group consisting of aluminum, silicon, titanium, tantalum, tungsten, and molybdenum.
- 35. A method of manufacturing a display device according to claim 28 wherein the gate electrode is formed over the semiconductor region.
- 36. A method of manufacturing a display device according to claim 28 wherein the display device is an active matrix type liquid crystal display device.
 - 37. A method of manufacturing a display device comprising:

forming a thin film transistor over a substrate, the thin film transistor comprising a semiconductor region and a gate electrode with a gate insulating film interposed therebetween;

forming a first layer comprising titanium on the semiconductor region, wherein the

first layer does not contain nitrogen;

forming a second layer comprising aluminum on the first layer; forming a third layer comprising titanium on the second layer; and forming a pixel electrode comprising a conductive oxide film on the third layer.

- 38. A method of manufacturing a display device according to claim 37 wherein the semiconductor region comprises crystalline silicon.
- 39. A method of manufacturing a display device according to claim 37 wherein the conductive oxide film comprises one selected from the group consisting of indium tin oxide, zinc oxide, and nickel oxide.
- 40. A method of manufacturing a display device according to claim 37 wherein the second layer comprises aluminum containing 1% silicon.
- 41. A method of manufacturing a display device according to claim 37 wherein the third layer comprises titanium nitride.
- 42. A method of manufacturing a display device according to claim 37 wherein the gate electrode comprises at least one selected from the group consisting of aluminum, silicon, titanium, tantalum, tungsten, and molybdenum.
- 43. A method of manufacturing a display device according to claim 37 wherein the gate electrode is formed over the semiconductor region.
- 44. A method of manufacturing a display device according to claim 37 wherein the display device is an active matrix type liquid crystal display device.
 - 45. A method of manufacturing a display device comprising:

forming a thin film transistor over a substrate, the thin film transistor comprising a semiconductor region and a gate electrode with a gate insulating film interposed therebetween;

forming a first layer comprising titanium on the semiconductor region, wherein the first layer does not contain nitrogen;

forming a second layer comprising aluminum on the first layer; forming a third layer comprising titanium on the second layer; forming a conductive oxide film on the third layer; and patterning the conductive oxide film so as to form a pixel electrode.

- 46. A method of manufacturing a display device according to claim 45 wherein the semiconductor region comprises crystalline silicon.
- 47. A method of manufacturing a display device according to claim 45 wherein the conductive oxide film comprises one selected from the group consisting of indium tin oxide, zinc oxide, and nickel oxide.
- 48. A method of manufacturing a display device according to claim 45 wherein the second layer comprises aluminum containing 1% silicon.
- 49. A method of manufacturing a display device according to claim 45 wherein the third layer comprises titanium nitride.
- 50. A method of manufacturing a display device according to claim 45 wherein the gate electrode comprises at least one selected from the group consisting of aluminum, silicon, titanium, tantalum, tungsten, and molybdenum.
- 51. A method of manufacturing a display device according to claim 45 wherein the gate electrode is formed over the semiconductor region.
- 52. A method of manufacturing a display device according to claim 45 wherein the display device is an active matrix type liquid crystal display device.
 - 53. A method of manufacturing a display device comprising:

forming a thin film transistor over a substrate, the thin film transistor comprising a semiconductor region and a gate electrode with a gate insulating film interposed therebetween;

forming a first layer comprising titanium on the semiconductor region, wherein a portion of the first layer in contact with the semiconductor region comprises titanium silicide;

forming a second layer comprising aluminum on the first layer; forming a third layer comprising titanium on the second layer; and forming a pixel electrode comprising a conductive oxide film on the third layer.

54. A method of manufacturing a display device according to claim 53 wherein the semiconductor region comprises crystalline silicon.

- 55. A method of manufacturing a display device according to claim 53 wherein the conductive oxide film comprises one selected from the group consisting of indium tin oxide, zinc oxide, and nickel oxide.
- 56. A method of manufacturing a display device according to claim 53 wherein the first layer comprises titanium nitride.
- 57. A method of manufacturing a display device according to claim 53 wherein the second layer comprises aluminum containing 1% silicon.
- 58. A method of manufacturing a display device according to claim 53 wherein the third layer comprises titanium nitride.
- 59. A method of manufacturing a display device according to claim 53 wherein the gate electrode comprises at least one selected from the group consisting of aluminum, silicon, titanium, tantalum, tungsten, and molybdenum.
- 60. A method of manufacturing a display device according to claim 53 wherein the gate electrode is formed over the semiconductor region.
- 61. A method of manufacturing a display device according to claim 53 wherein the display device is an active matrix type liquid crystal display device.
 - 62. A method of manufacturing a display device comprising:

forming a thin film transistor over a substrate, the thin film transistor comprising a semiconductor region and a gate electrode with a gate insulating film interposed therebetween;

forming a first layer comprising titanium on the semiconductor region, wherein a portion of the first layer in contact with the semiconductor region comprises titanium silicide;

forming a second layer comprising aluminum on the first layer; forming a third layer comprising titanium on the second layer; forming a conductive oxide film on the third layer; and patterning the conductive oxide film so as to form a pixel electrode.

63. A method of manufacturing a display device according to claim 62 wherein the semiconductor region comprises crystalline silicon.

- 64. A method of manufacturing a display device according to claim 62 wherein the conductive oxide film comprises one selected from the group consisting of indium tin oxide, zinc oxide, and nickel oxide.
- 65. A method of manufacturing a display device according to claim 62 wherein the first layer comprises titanium nitride.
- 66. A method of manufacturing a display device according to claim 62 wherein the second layer comprises aluminum containing 1% silicon.
- 67. A method of manufacturing a display device according to claim 62 wherein the third layer comprises titanium nitride.
- 68. A method of manufacturing a display device according to claim 62 wherein the gate electrode comprises at least one selected from the group consisting of aluminum, silicon, titanium, tantalum, tungsten, and molybdenum.
- 69. A method of manufacturing a display device according to claim 62 wherein the gate electrode is formed over the semiconductor region.
- 70. A method of manufacturing a display device according to claim 62 wherein the display device is an active matrix type liquid crystal display device.